Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.158”**

**.076”**

**OUTPUT**

**OUTPUT**

**OUTPUT**

**OUTPUT**

**ADJ**

**INPUT**

**INPUT**

**INPUT**

**INPUT**

**ENABLE**

**MIC29300-AC**

**MASK**

**REF**

**Top Material: Al**

**Backside Material: Cr/Ni/Ag**

**Bond Pad Size: .003” X .003” min.**

**Backside Potential: GND**

**Mask Ref: MIC29300-AC**

**APPROVED BY: DK DIE SIZE .076” X .158” DATE: 1/18/17**

**MFG: MICREL THICKNESS .014” P/N: MIC29300**

**DG 10.1.2**

#### Rev B, 7/1